

Title (en)
ENCASING ARRANGEMENT FOR A SEMICONDUCTOR COMPONENT

Title (de)
GEHÄUSEANORDNUNG EINES HALBLEITERBAUSTEINS

Title (fr)
ENSEMBLE BOITIER D'UN COMPOSANT A SEMI-CONDUCTEUR

Publication
EP 1238426 A2 20020911 (DE)

Application
EP 00990529 A 20001213

Priority
• DE 0004437 W 20001213
• DE 19960246 A 19991214

Abstract (en)
[origin: WO0145166A2] The invention relates to an encasing arrangement for a semi-conductor component, which comprises a semi-conductor chip (2), a circuit board (8), upon which the semi-conductor component (1) is mounted and a support layer (3), arranged between the semi-conductor chip (2) and the circuit board (8) for rewiring the wiring connectors (11) for the semi-conductor chip (2) on the circuit board (8). The support layer (3) is linked to the circuit board (8), by means of soldered connections (6) and a filler (4) serves to mechanically connect the semi-conductor chip (2) and the soldered connections (6). A metal layer (5) is arranged on the support layer (3), which is connected to soldered connections (6). At least one shaped element (7), made of thermally conductive material, is arranged on the metal layer (5) and is thermally connected to the metal layer (5). The encasing arrangement thus achieves an improved conductivity of the power loss from the incorporated semi-conductor chip (2), which is to be drained off, whereby the desired mechanical properties of the encasing arrangement are maintained.

IPC 1-7
H01L 23/498; **H01L 23/367**; **H01L 23/31**

IPC 8 full level
H01L 23/31 (2006.01); **H01L 23/367** (2006.01)

CPC (source: EP US)
H01L 23/3107 (2013.01 - EP US); **H01L 23/3677** (2013.01 - EP US); **H01L 24/32** (2013.01 - EP US); **H01L 2224/27013** (2013.01 - EP US); **H01L 2224/83051** (2013.01 - EP US); **H01L 2924/01005** (2013.01 - EP US); **H01L 2924/01029** (2013.01 - EP US); **H01L 2924/01068** (2013.01 - EP US); **H01L 2924/01078** (2013.01 - EP US); **H01L 2924/01082** (2013.01 - EP US); **H01L 2924/01087** (2013.01 - EP US); **H01L 2924/30105** (2013.01 - EP US); **H01L 2924/30107** (2013.01 - EP US); **H01L 2924/3025** (2013.01 - EP US)

Citation (search report)
See references of WO 0145166A2

Designated contracting state (EPC)
AT DE

DOCDB simple family (publication)
WO 0145166 A2 20010621; **WO 0145166 A3 20020411**; DE 19960246 A1 20010705; EP 1238426 A2 20020911; US 2005040517 A1 20050224; US 7208827 B2 20070424

DOCDB simple family (application)
DE 0004437 W 20001213; DE 19960246 A 19991214; EP 00990529 A 20001213; US 14989204 A 20041001